

PCN Number:	20200323000.1		PCN Date:	Mar 23, 2020	
Title:	Qualification of AIZU as an additional Fab Site option for select CMOS7 devices				
Customer Contact:	PCN Manager	Dept:	Quality Services		
Proposed 1st Ship Date:	Jun 23, 2020	Estimated Sample Availability:	Date provided at sample request.		
Change Type:					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
		<input type="checkbox"/>	Part number change		

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of its AIZU fabrication facility as an additional Wafer Fab source for the selected devices listed in "Product Affected" section.

Current Sites			Additional Sites		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
MAINEFAB	CMOS7	200mm	AIZU	CMOS7	200mm

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current

Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City
MAINEFAB	CUA	USA	South Portland

New Fab Site

Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City
AIZU	CU2	JPN	Aizuwakamatsu-shi

Sample product shipping label (not actual product label)

 TEXAS INSTRUMENTS

MADE IN: Malaysia
2DC: 20:

MSL 2 / 260C / 1 YEAR	SEAL DT
MSL 1 / 235C / UNLIM	03/29/04

OPT:
ITEM:

LBL: 5A (L)T0:1750



(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483S12
(P)
(2P) REV: (V) 0033317
(20L) CS0: SHE (21L) CCO: USA
(22L) AS0: MLA (23L) ACO: MYS

Product Affected Group:

LM73CIMK-0/NOPB	LM73CIMKX-0/NOPB
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Qualification Report

Approve Date 27-Jan-2020

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LM73CIMKX0NOPB	QBS Process Reference: LM3668QDNTRQ1
PC	Preconditioning Level 1	Level 1 260C	1/320/0	3/800/0
HTOL	Life Test, 125C	1000 Hours	1/80/2 (Note 1)	3/231/0
AC	Autoclave 121C	96 Hours	1/77/0	-
UHAST	Unbiased HAST 130C/85%RH	96 Hours	-	3/231/0
HAST	Biased HAST, 130C/85%RH	96 Hours	1/77/0	3/231/0
TC	Temperature Cycle, -65/150C	500CYC	1/77/0	3/231/0
HTSL	High Temp Storage Bake 170C	420 Hours	1/77/0	-
HTSL	High Temp Storage Bake 150C	1000 Hours	-	3/231/0
HBM	ESD - HBM	1000 V	1/3/0	-
CDM	ESD - CDM	750 V	1/3/0	-
LU	Latch-up	Per JESD78	1/6/0	-
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	-
WBS	Wire Bond Shear	Cpk > 1.67	1/80/0	-
WBP	Wire Bond Pull	Cpk > 1.67	1/80/0	-

- QBS: Qual By Similarity

- Qual Device LM73CIMKX-0/NOPB is qualified at LEVEL 1-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7 eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7 eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

Note 1: Two units failed ATE after 1000 hours oplife. Units failed due to data retention issue. Production bake was implemented to remove weak device at wafer sort

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

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